

ON Semiconductor®

# FDC640P

## P-Channel 2.5V PowerTrench® Specified MOSFET

## **General Description**

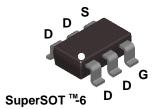
This P-Channel 2.5V specified MOSFET uses a rugged gate version of ON Semiconductor's advanced PowerTrench process. It has been optimized for power management applications with a wide range of gate drive voltage (2.5V – 12V).

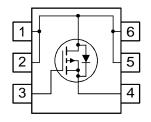
## **Applications**

- Battery management
- · Load switch
- Battery protection

### **Features**

- -4.5 A, -20 V  $R_{DS(ON)} = 0.053~\Omega @ V_{GS} = -4.5~V$   $R_{DS(ON)} = 0.080~\Omega @ V_{GS} = -2.5~V$
- Rugged gate rating (±12V)
- · Fast switching speed
- High performance trench technology for extremely low  $R_{\text{DS}(\text{ON})}$





Absolute Maximum Ratings T<sub>A=25°C</sub> unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>DSS</sub>	Drain-Source Voltage		-20	V
V <sub>GSS</sub>	Gate-Source Voltage		±12	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1a)	-4.5	A
	- Pulsed		-20	
P <sub>D</sub>	Maximum Power Dissipation	(Note 1a)	1.6	W
		(Note 1b)	0.8	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temp	erature Range	-55 to +150	°C

## **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	30	°C/W

**Package Marking and Ordering Information** 

Device Marking	Device	Reel Size	Tape width	Quantity	
.640	FDC640P	7"	8mm	3000 units	

Electric	Electrical Characteristics T <sub>A</sub> = 25°C unless otherwise noted						
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Off Char	acteristics		•			•	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-20			V	
ΔBV <sub>DSS</sub> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$ , Referenced to $25^{\circ}\text{C}$		-14		mV/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V},  V_{GS} = 0 \text{ V}$			-1	μΑ	
I <sub>GSSF</sub>	Gate-Body Leakage, Forward	$V_{GS} = 12 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA	
I <sub>GSSR</sub>	Gate-Body Leakage, Reverse	$V_{GS} = -12 \text{ V},  V_{DS} = 0 \text{ V}$			-100	nA	
On Char	acteristics (Note 2)						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.6	-1.0	-1.5	V	
$\Delta V_{GS(th)} \ \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$ , Referenced to $25^{\circ}\text{C}$		3		mV/°C	
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	$V_{GS} = -4.5 \text{ V},  I_D = -4.5 \text{ A}$ $V_{GS} = -2.5 \text{ V},  I_D = -3.6 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -4.5 \text{ A}, T_J = 125^{\circ}\text{C}$		0.039 0.062 0.053	0.053 0.080 0.077	Ω	
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS} = -4.5 \text{ V}, \qquad V_{DS} = -5 \text{ V}$	-20			Α	
<b>g</b> FS	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -4.5 \text{ A}$		16		S	
Dvnamio	Characteristics						
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -10 \text{ V},  V_{GS} = 0 \text{ V},$		890		pF	
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		244		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			123		pF	
Switchin	ng Characteristics (Note 2)		•	•		•	
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = -10 \text{ V}, \qquad I_{D} = -1 \text{ A}, $ $V_{GS} = -4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		12	22	ns	
t <sub>r</sub>	Turn-On Rise Time			9	18	ns	
t <sub>d(off)</sub>	Turn-Off Delay Time	7		24	38	ns	
t <sub>f</sub>	Turn-Off Fall Time	7		13	23	ns	
Qg	Total Gate Charge	$V_{DS} = -10 \text{ V}, \qquad I_{D} = -4.5 \text{ A}, \\ V_{GS} = -4.5 \text{ V}$		9	13	nC	
Q <sub>gs</sub>	Gate-Source Charge			2		nC	
$Q_{gd}$	Gate-Drain Charge	1		3		nC	
Drain-S	ource Diode Characteristics	and Maximum Ratings					
l <sub>s</sub>	Maximum Continuous Drain-Source				-1.3	Α	
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V},  I_S = -1.3 \text{ A}  \text{(Note 2)}$		-0.7	-1.2	V	

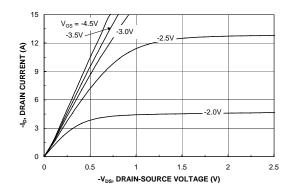
<sup>1.</sup>  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.

a. 78°C/W when mounted on a 1in² pad of 2oz copper on FR-4 board.

b. 156°C/W when mounted on a minimum pad.

<sup>2.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%

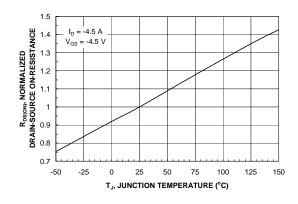
## **Typical Characteristics**



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Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.



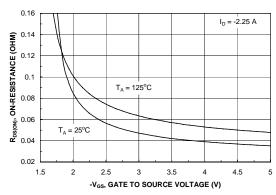
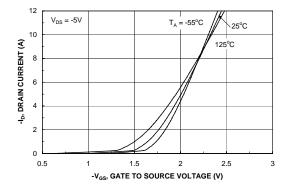


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



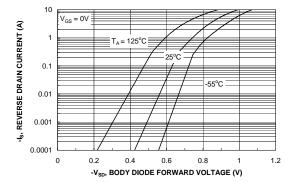
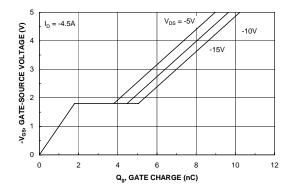


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## **Typical Characteristics**



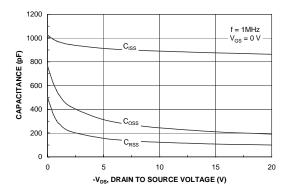
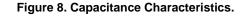
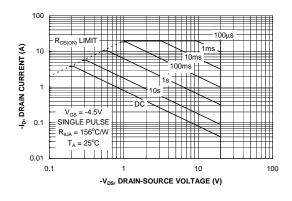


Figure 7. Gate Charge Characteristics.





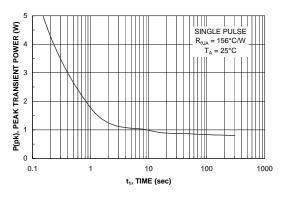


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

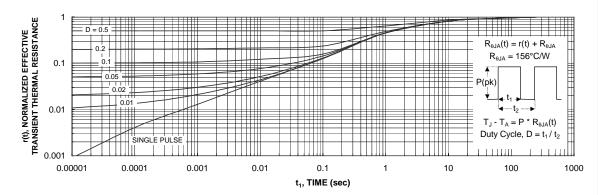


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b Transient thermal response will change depending on the circuit board design.

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